



MICROELECTRONIC ENGINEERING

Microelectronic Engineering 84 (2007) 973-976

www.elsevier.com/locate/mee

Fluorinated materials for UV nanoimprint lithography

Yasuhide Kawaguchi *, Fumiko Nonaka, Yasuhiro Sanada

Asahi Glass Co., Ltd., 1150, Hazawa-cho, Kanagawa-ku, Yokohama-shi, Kanagawa-ken, 221-8755, Japan Available online 3 February 2007

Abstract

The "demolding" is the important key for UV nanoimprint lithography (UV-NIL) which attracts a lot of attention recently as microfabrication technique. Then, we present in this paper, new fluorinated mold material and new fluorinated photosensitive polymer which are suitable for the UV-NIL because of their high transparency and excellent mold-release characteristics. By using our mold material "F-template", the process cost can be drastically reduced because it can be used as replicated mold instead of using expensive quartz master mold. F-template requires no releasing agent is another advantage. We also developed photosensitive polymer "NIF-A-1" which has high transparency, good mold-releasing ability and good dry etching resistance. Unlike the common photosensitive polymer, NIF-A-1 did not need a releasing agent on the mold.

© 2007 Elsevier B.V. All rights reserved.

Keywords: Nanoimprint; UV; Fluorinated material; Mold; Photosensitive polymer